

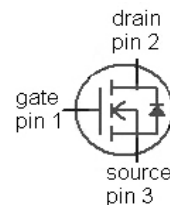
## OptiMOS® 2 Power-Transistor

### Features

- Ideal for high-frequency dc/dc converters
- Qualified according to JEDEC<sup>1)</sup> for target application
- N-channel, logic level
- Excellent gate charge x  $R_{DS(on)}$  product (FOM)
- Superior thermal resistance
- 175 °C operating temperature
- Pb-free lead plating; RoHS compliant

### Product Summary

|                                |    |    |
|--------------------------------|----|----|
| $V_{DS}$                       | 25 | V  |
| $R_{DS(on),max}$ (SMD version) | 6  | mΩ |
| $I_D$                          | 50 | A  |



| Type    | IPDH6N03LA G                                                                       | IPFH6N03LA G                                                                       | IPSH6N03LA G                                                                        | IPUH6N03LA G                                                                         |
|---------|------------------------------------------------------------------------------------|------------------------------------------------------------------------------------|-------------------------------------------------------------------------------------|--------------------------------------------------------------------------------------|
|         |  |  |  |  |
| Package | PG-TO252-3-11                                                                      | PG-TO252-3-23                                                                      | PG-TO251-3-11                                                                       | PG-TO251-3-1                                                                         |
| Marking | H6N03LA                                                                            | H6N03LA                                                                            | H6N03LA                                                                             | H6N03LA                                                                              |

Maximum ratings, at  $T_j=25\text{ °C}$ , unless otherwise specified

| Parameter                           | Symbol            | Conditions                                                                                           | Value       | Unit  |
|-------------------------------------|-------------------|------------------------------------------------------------------------------------------------------|-------------|-------|
| Continuous drain current            | $I_D$             | $T_C=25\text{ °C}^{2)}$                                                                              | 50          | A     |
|                                     |                   | $T_C=100\text{ °C}$                                                                                  | 50          |       |
| Pulsed drain current                | $I_{D,pulse}$     | $T_C=25\text{ °C}^{3)}$                                                                              | 350         |       |
| Avalanche energy, single pulse      | $E_{AS}$          | $I_D=50\text{ A}$ , $R_{GS}=25\text{ Ω}$                                                             | 150         | mJ    |
| Reverse diode $dv/dt$               | $dv/dt$           | $I_D=50\text{ A}$ , $V_{DS}=20\text{ V}$ ,<br>$di/dt=200\text{ A/μs}$ ,<br>$T_{j,max}=175\text{ °C}$ | 6           | kV/μs |
| Gate source voltage <sup>4)</sup>   | $V_{GS}$          |                                                                                                      | ±20         | V     |
| Power dissipation                   | $P_{tot}$         | $T_C=25\text{ °C}$                                                                                   | 71          | W     |
| Operating and storage temperature   | $T_j$ , $T_{stg}$ |                                                                                                      | -55 ... 175 | °C    |
| IEC climatic category; DIN IEC 68-1 |                   |                                                                                                      | 55/175/56   |       |

| Parameter | Symbol | Conditions | Values |      |      | Unit |
|-----------|--------|------------|--------|------|------|------|
|           |        |            | min.   | typ. | max. |      |

#### Thermal characteristics

|                                     |            |                                              |   |   |     |     |
|-------------------------------------|------------|----------------------------------------------|---|---|-----|-----|
| Thermal resistance, junction - case | $R_{thJC}$ |                                              | - | - | 2.1 | K/W |
| SMD version, device on PCB          | $R_{thJA}$ | minimal footprint                            | - | - | 75  |     |
|                                     |            | 6 cm <sup>2</sup> cooling area <sup>5)</sup> | - | - | 50  |     |

#### Electrical characteristics, at $T_j=25\text{ °C}$ , unless otherwise specified

#### Static characteristics

|                                  |               |                                                            |     |     |      |               |
|----------------------------------|---------------|------------------------------------------------------------|-----|-----|------|---------------|
| Drain-source breakdown voltage   | $V_{(BR)DSS}$ | $V_{GS}=0\text{ V}, I_D=1\text{ mA}$                       | 25  | -   | -    | V             |
| Gate threshold voltage           | $V_{GS(th)}$  | $V_{DS}=V_{GS}, I_D=30\text{ }\mu\text{A}$                 | 1.2 | 1.6 | 2    |               |
| Zero gate voltage drain current  | $I_{DSS}$     | $V_{DS}=25\text{ V}, V_{GS}=0\text{ V}, T_j=25\text{ °C}$  | -   | 0.1 | 1    | $\mu\text{A}$ |
|                                  |               | $V_{DS}=25\text{ V}, V_{GS}=0\text{ V}, T_j=125\text{ °C}$ | -   | 10  | 100  |               |
| Gate-source leakage current      | $I_{GSS}$     | $V_{GS}=20\text{ V}, V_{DS}=0\text{ V}$                    | -   | 10  | 100  | nA            |
| Drain-source on-state resistance | $R_{DS(on)}$  | $V_{GS}=4.5\text{ V}, I_D=30\text{ A}$                     | -   | 8.2 | 10.2 | m $\Omega$    |
|                                  |               | $V_{GS}=4.5\text{ V}, I_D=30\text{ A},$<br>IPD version     | -   | 8   | 10   |               |
|                                  |               | $V_{GS}=10\text{ V}, I_D=50\text{ A}$                      | -   | 5.2 | 6.2  |               |
|                                  |               | $V_{GS}=10\text{ V}, I_D=50\text{ A},$<br>IPD version      | -   | 5   | 6    |               |
| Gate resistance                  | $R_G$         |                                                            | -   | 1.3 | -    | $\Omega$      |
| Transconductance                 | $g_{fs}$      | $ V_{DS} >2 I_D R_{DS(on)max},$<br>$I_D=50\text{ A}$       | 35  | 69  | -    | S             |

<sup>1)</sup> J-STD20 and JESD22

<sup>2)</sup> Current is limited by bondwire; with an  $R_{thJC}=2.1\text{ K/W}$  the chip is able to carry 80 A.

<sup>3)</sup> See figure 3

<sup>4)</sup>  $T_{j,max}=150\text{ °C}$  and duty cycle  $D<0.25$  for  $V_{GS}<-5\text{ V}$

<sup>5)</sup> Device on 40 mm x 40 mm x 1.5 mm epoxy PCB FR4 with 6 cm<sup>2</sup> (one layer, 70  $\mu\text{m}$  thick) copper area for drain connection. PCB is vertical in still air.

| Parameter | Symbol | Conditions | Values |      |      | Unit |
|-----------|--------|------------|--------|------|------|------|
|           |        |            | min.   | typ. | max. |      |

#### Dynamic characteristics

|                              |              |                                                                                 |   |      |      |    |
|------------------------------|--------------|---------------------------------------------------------------------------------|---|------|------|----|
| Input capacitance            | $C_{iss}$    | $V_{GS}=0\text{ V}, V_{DS}=15\text{ V},$<br>$f=1\text{ MHz}$                    | - | 1800 | 2390 | pF |
| Output capacitance           | $C_{oss}$    |                                                                                 | - | 690  | 920  |    |
| Reverse transfer capacitance | $C_{rss}$    |                                                                                 | - | 85   | 130  |    |
| Turn-on delay time           | $t_{d(on)}$  | $V_{DD}=15\text{ V}, V_{GS}=10\text{ V},$<br>$I_D=25\text{ A}, R_G=2.7\ \Omega$ | - | 6    | 9    | ns |
| Rise time                    | $t_r$        |                                                                                 | - | 5.4  | 8    |    |
| Turn-off delay time          | $t_{d(off)}$ |                                                                                 | - | 23   | 34   |    |
| Fall time                    | $t_f$        |                                                                                 | - | 4.2  | 6.3  |    |

#### Gate Charge Characteristics<sup>6)</sup>

|                              |               |                                                                           |   |     |     |    |
|------------------------------|---------------|---------------------------------------------------------------------------|---|-----|-----|----|
| Gate to source charge        | $Q_{gs}$      | $V_{DD}=15\text{ V}, I_D=25\text{ A},$<br>$V_{GS}=0\text{ to }5\text{ V}$ | - | 5.9 | 7.8 | nC |
| Gate charge at threshold     | $Q_{g(th)}$   |                                                                           | - | 2.9 | 3.8 |    |
| Gate to drain charge         | $Q_{gd}$      |                                                                           | - | 4.1 | 6.1 |    |
| Switching charge             | $Q_{sw}$      |                                                                           | - | 7.1 | 10  |    |
| Gate charge total            | $Q_g$         |                                                                           | - | 14  | 19  |    |
| Gate plateau voltage         | $V_{plateau}$ |                                                                           | - | 3.3 | -   | V  |
| Gate charge total, sync. FET | $Q_{g(sync)}$ | $V_{DS}=0.1\text{ V},$<br>$V_{GS}=0\text{ to }5\text{ V}$                 | - | 13  | 17  | nC |
| Output charge                | $Q_{oss}$     | $V_{DD}=15\text{ V}, V_{GS}=0\text{ V}$                                   | - | 15  | 20  |    |

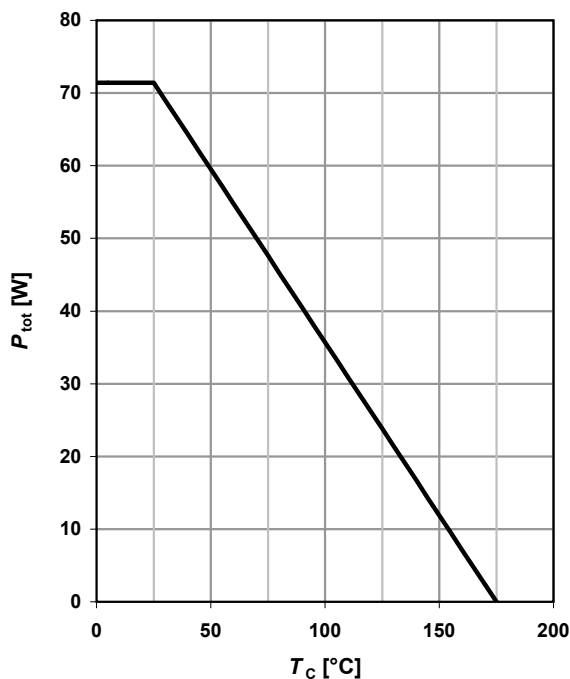
#### Reverse Diode

|                                  |               |                                                                   |   |      |     |    |
|----------------------------------|---------------|-------------------------------------------------------------------|---|------|-----|----|
| Diode continuous forward current | $I_S$         | $T_C=25\text{ °C}$                                                | - | -    | 50  | A  |
| Diode pulse current              | $I_{S,pulse}$ |                                                                   | - | -    | 350 |    |
| Diode forward voltage            | $V_{SD}$      | $V_{GS}=0\text{ V}, I_F=50\text{ A},$<br>$T_j=25\text{ °C}$       | - | 0.93 | 1.2 | V  |
| Reverse recovery charge          | $Q_{rr}$      | $V_R=15\text{ V}, I_F=I_S,$<br>$di_F/dt=400\text{ A}/\mu\text{s}$ | - | -    | 10  | nC |

<sup>6)</sup> See figure 16 for gate charge parameter definition

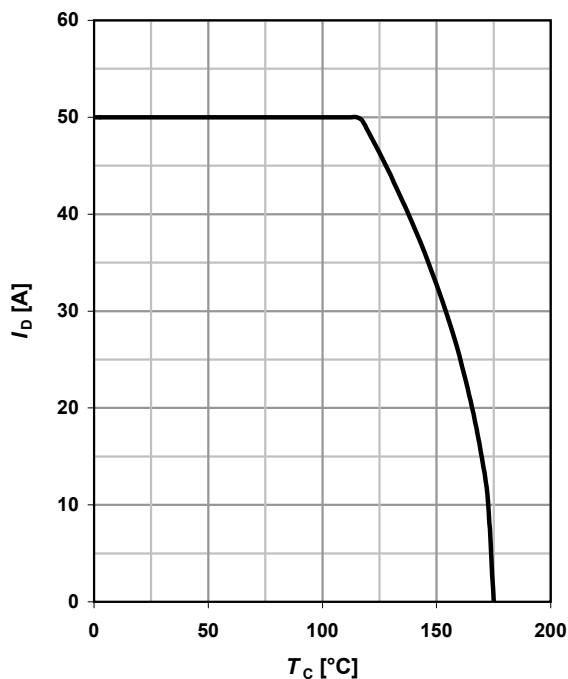
### 1 Power dissipation

$$P_{\text{tot}} = f(T_C)$$



### 2 Drain current

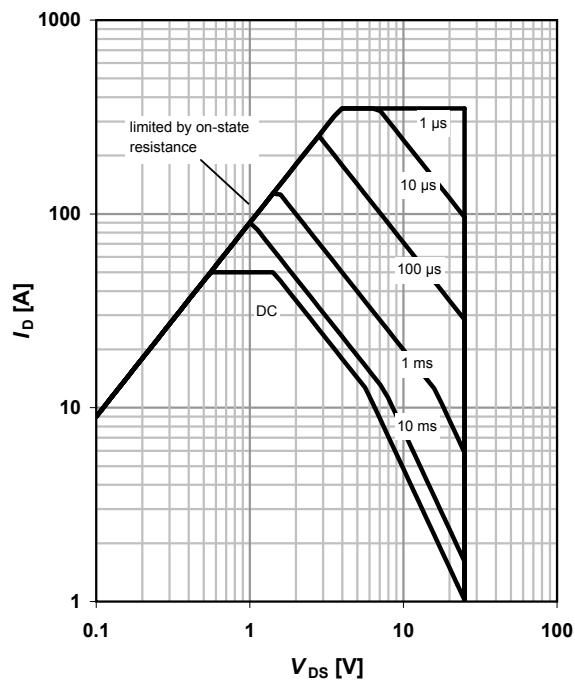
$$I_D = f(T_C); V_{GS} \geq 10 \text{ V}$$



### 3 Safe operating area

$$I_D = f(V_{DS}); T_C = 25 \text{ °C}; D = 0$$

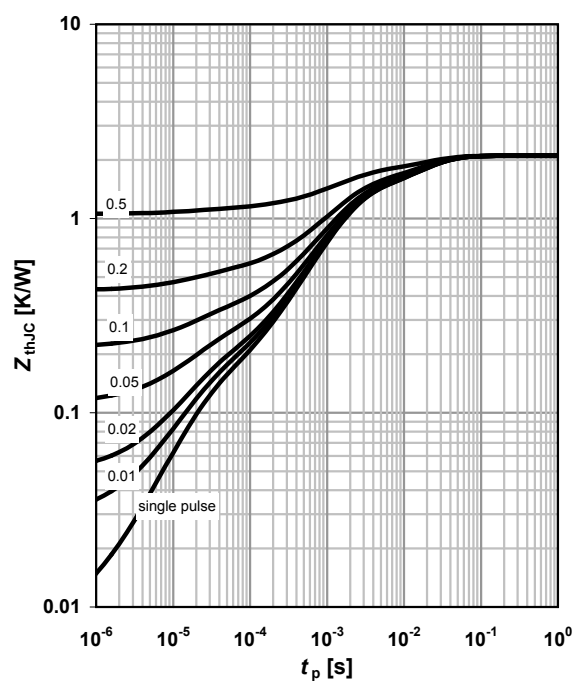
parameter:  $t_p$



### 4 Max. transient thermal impedance

$$Z_{\text{thJC}} = f(t_p)$$

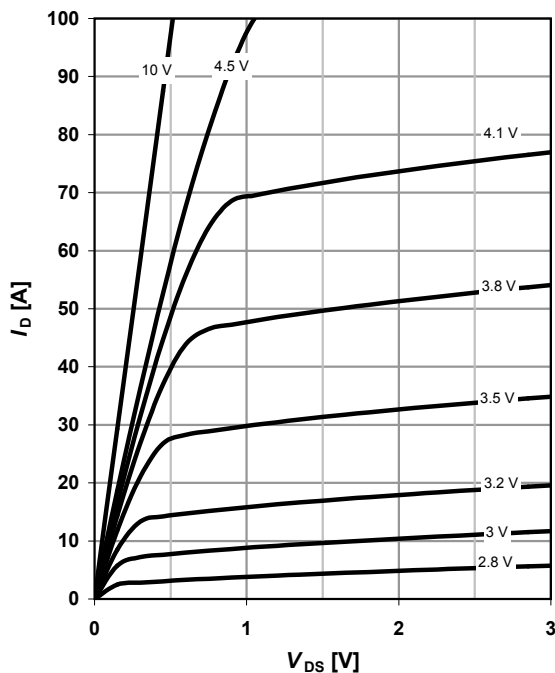
parameter:  $D = t_p / T$



### 5 Typ. output characteristics

$$I_D = f(V_{DS}); T_j = 25^\circ\text{C}$$

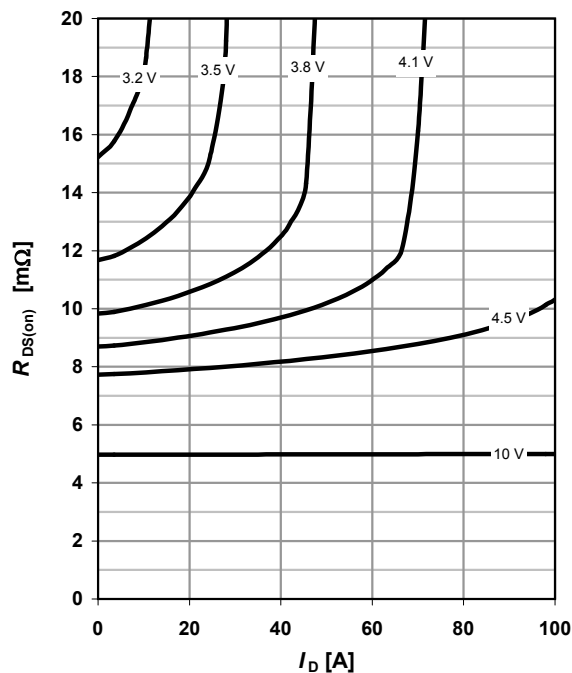
parameter:  $V_{GS}$



### 6 Typ. drain-source on resistance

$$R_{DS(on)} = f(I_D); T_j = 25^\circ\text{C}$$

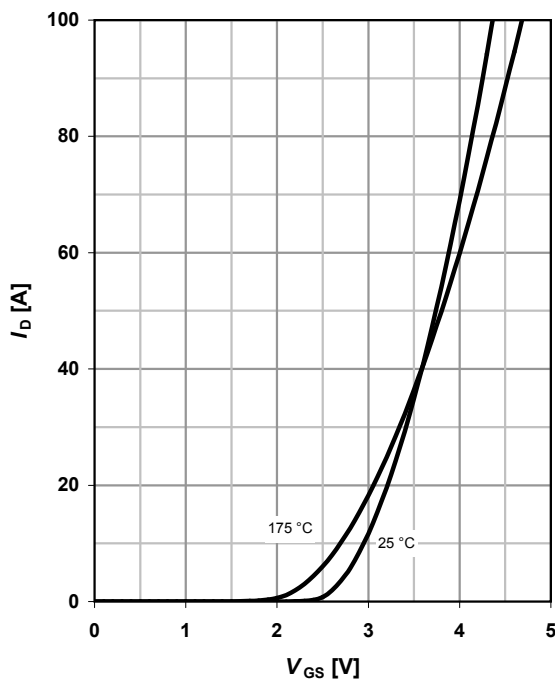
parameter:  $V_{GS}$



### 7 Typ. transfer characteristics

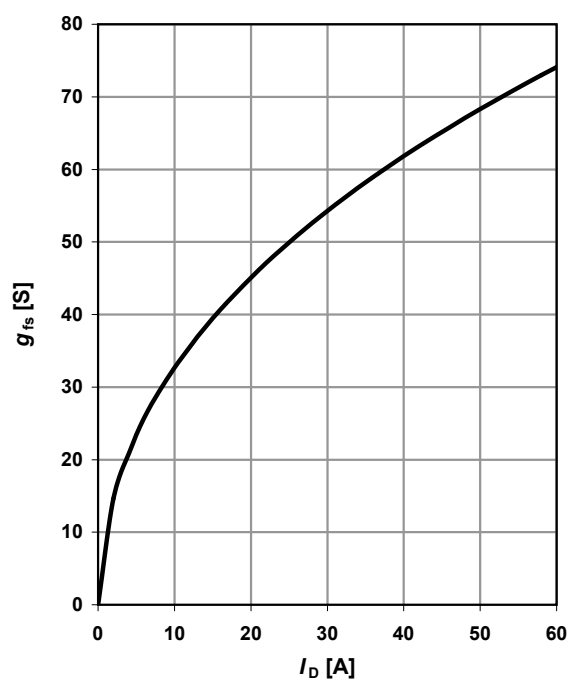
$$I_D = f(V_{GS}); |V_{DS}| > 2|I_D|R_{DS(on)max}$$

parameter:  $T_j$



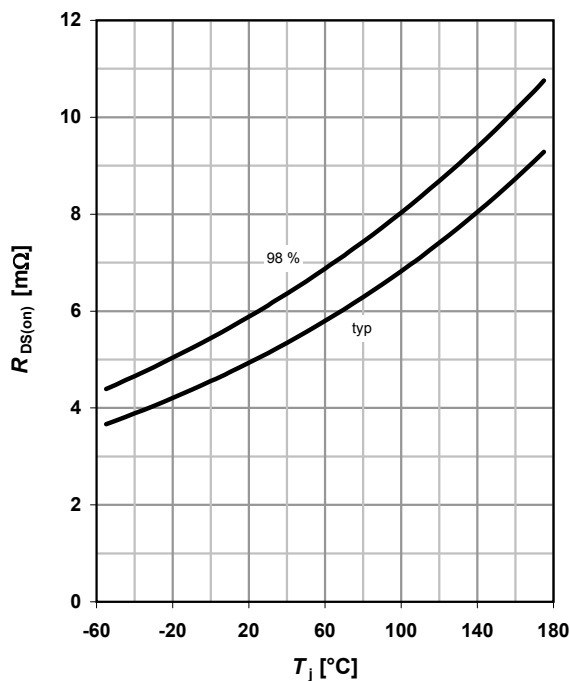
### 8 Typ. forward transconductance

$$g_{fs} = f(I_D); T_j = 25^\circ\text{C}$$



### 9 Drain-source on-state resistance

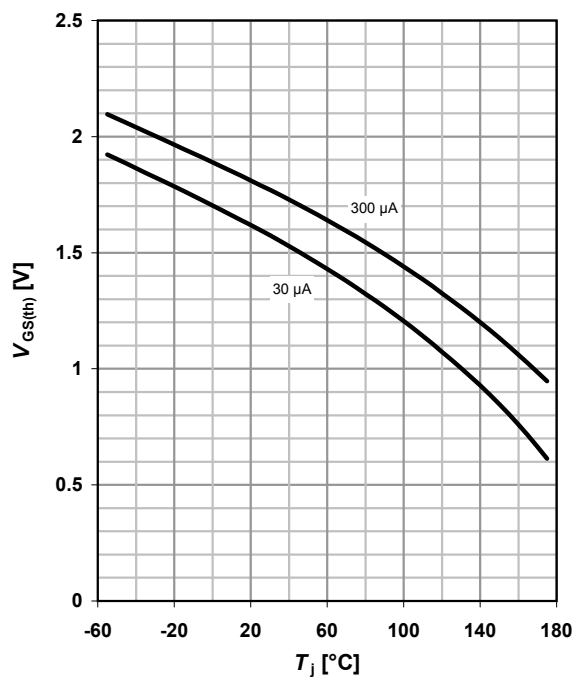
$$R_{DS(on)} = f(T_j); I_D = 50 \text{ A}; V_{GS} = 10 \text{ V}$$



### 10 Typ. gate threshold voltage

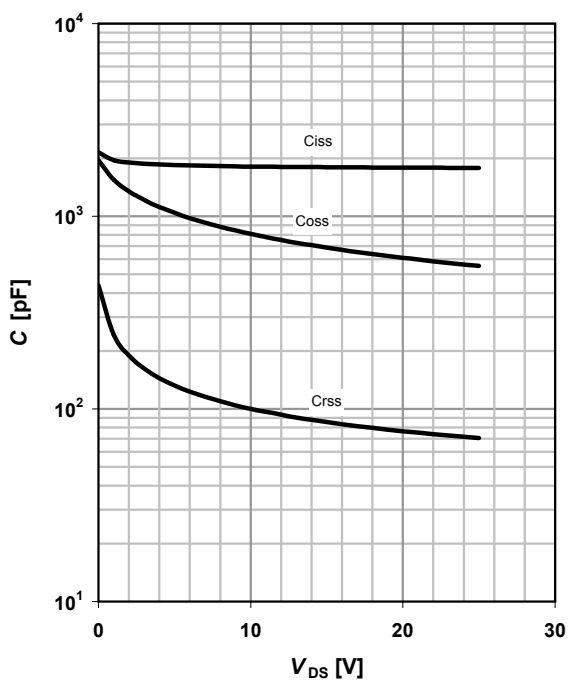
$$V_{GS(th)} = f(T_j); V_{GS} = V_{DS}$$

parameter:  $I_D$



### 11 Typ. capacitances

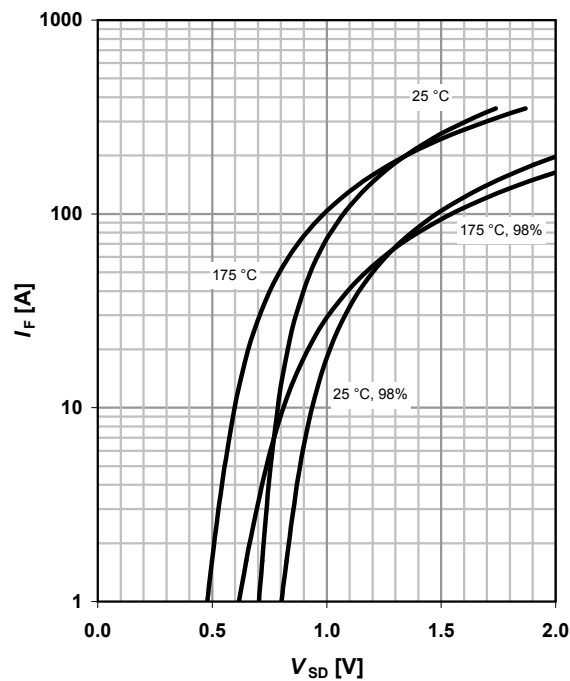
$$C = f(V_{DS}); V_{GS} = 0 \text{ V}; f = 1 \text{ MHz}$$



### 12 Forward characteristics of reverse diode

$$I_F = f(V_{SD})$$

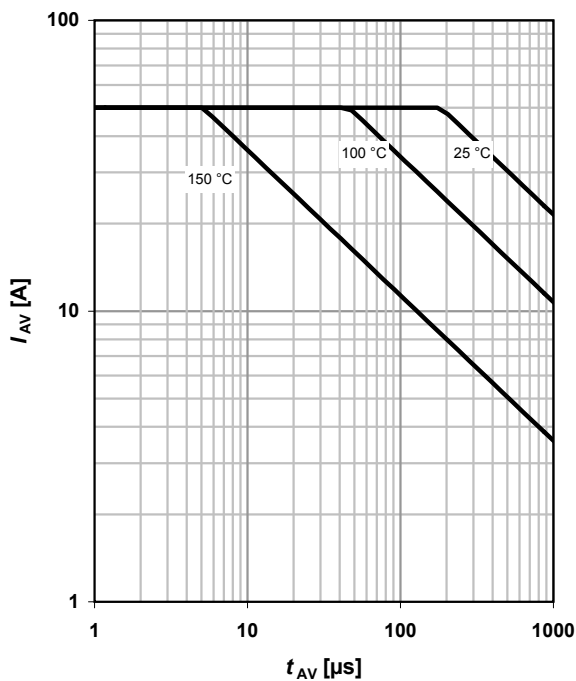
parameter:  $T_j$



### 13 Avalanche characteristics

$$I_{AS}=f(t_{AV}); R_{GS}=25\ \Omega$$

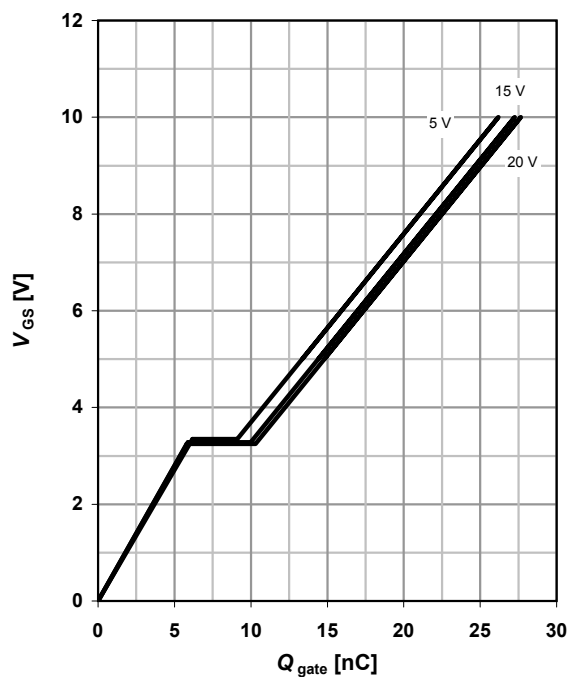
parameter:  $T_{j(\text{start})}$



### 14 Typ. gate charge

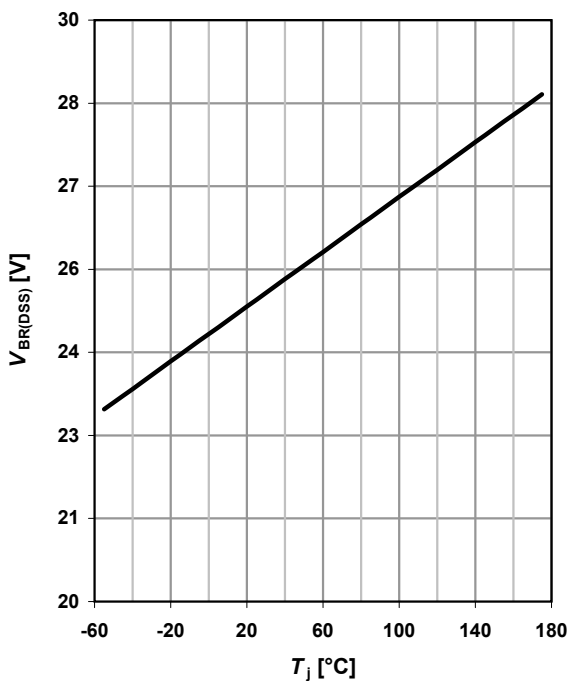
$$V_{GS}=f(Q_{\text{gate}}); I_D=25\ \text{A pulsed}$$

parameter:  $V_{DD}$



### 15 Drain-source breakdown voltage

$$V_{BR(DSS)}=f(T_j); I_D=1\ \text{mA}$$

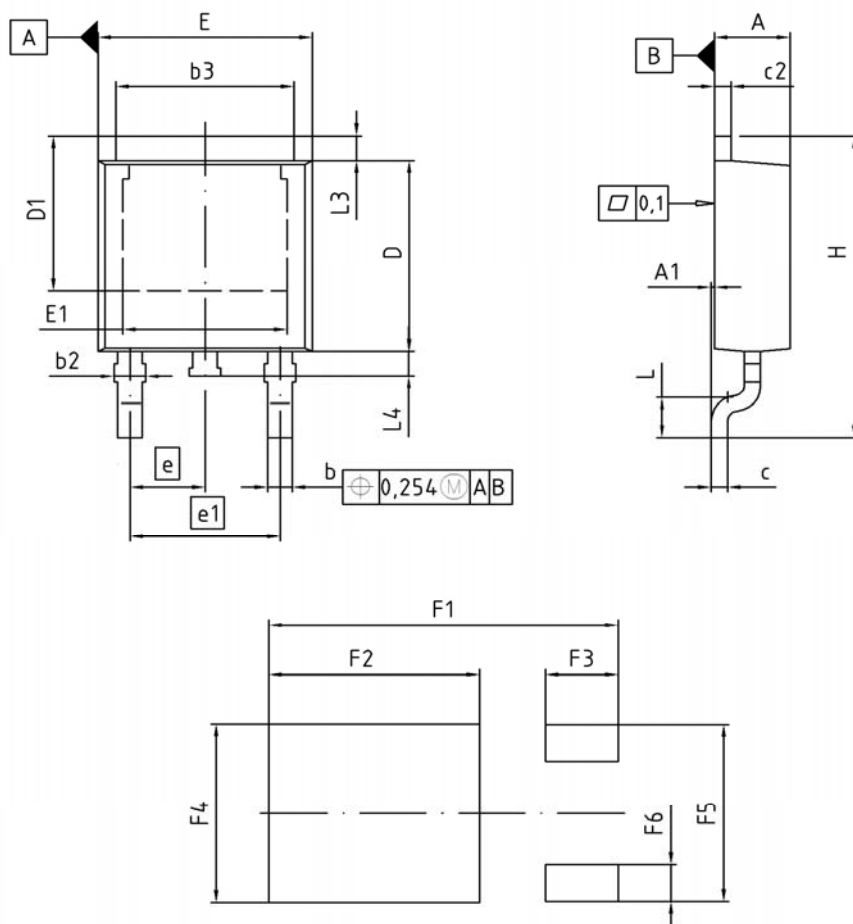


### 16 Gate charge waveforms



Package Outline

PG-TO252-3-11

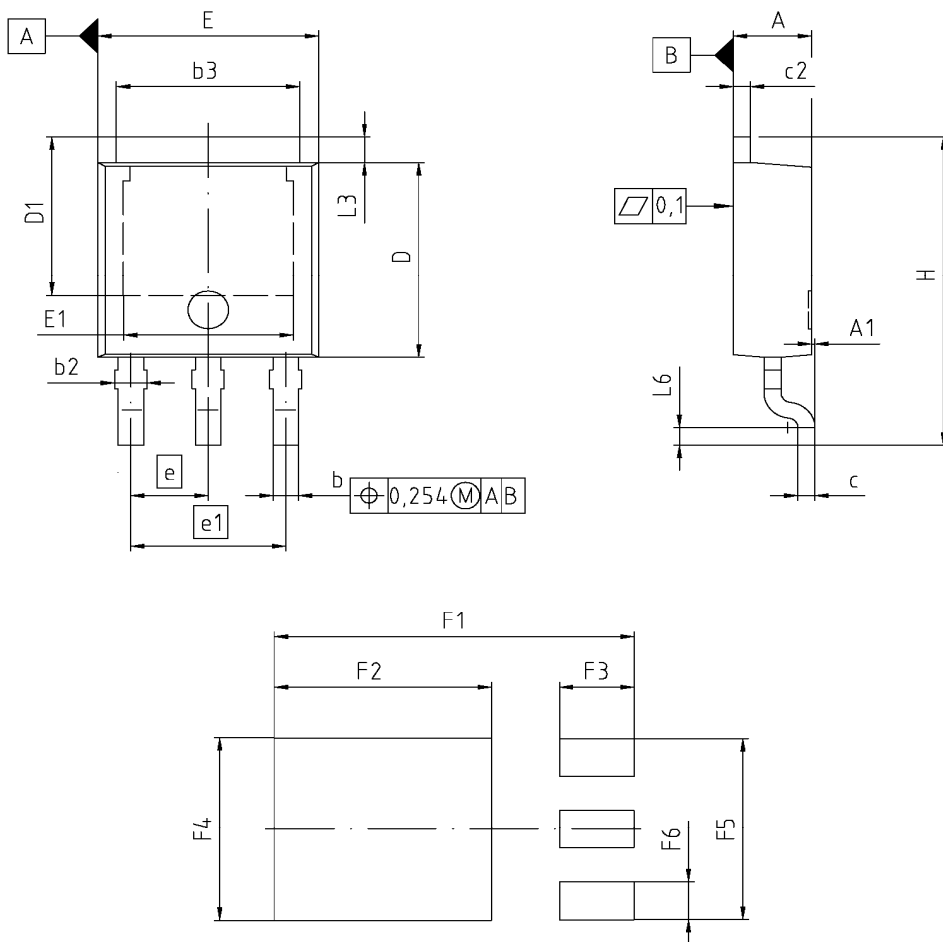


| DIM | MILLIMETERS |       | INCHES |       |
|-----|-------------|-------|--------|-------|
|     | MIN         | MAX   | MIN    | MAX   |
| A   | 2.16        | 2.41  | 0.085  | 0.095 |
| A1  | 0.00        | 0.15  | 0.000  | 0.006 |
| b   | 0.64        | 0.89  | 0.025  | 0.035 |
| b2  | 0.65        | 1.15  | 0.026  | 0.045 |
| b3  | 5.00        | 5.50  | 0.197  | 0.217 |
| c   | 0.46        | 0.60  | 0.018  | 0.024 |
| c2  | 0.46        | 0.98  | 0.018  | 0.039 |
| D   | 5.97        | 6.22  | 0.235  | 0.245 |
| D1  | 5.02        | 5.84  | 0.198  | 0.230 |
| E   | 6.40        | 6.73  | 0.252  | 0.265 |
| E1  | 4.70        | 5.21  | 0.185  | 0.205 |
| e   | 2.29        |       | 0.090  |       |
| e1  | 4.57        |       | 0.180  |       |
| N   | 3           |       | 3      |       |
| H   | 9.40        | 10.48 | 0.370  | 0.413 |
| L   | 1.18        | 1.70  | 0.046  | 0.067 |
| L3  | 0.90        | 1.25  | 0.035  | 0.049 |
| L4  | 0.51        | 1.00  | 0.020  | 0.039 |
| F1  | 10.50       | 10.70 | 0.413  | 0.421 |
| F2  | 6.30        | 6.50  | 0.248  | 0.256 |
| F3  | 2.10        | 2.30  | 0.083  | 0.091 |
| F4  | 5.70        | 5.90  | 0.224  | 0.232 |
| F5  | 5.66        | 5.86  | 0.223  | 0.231 |
| F6  | 1.10        | 1.30  | 0.043  | 0.051 |

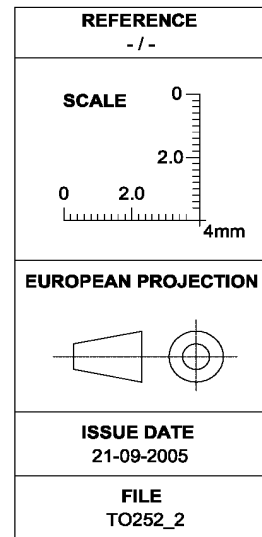
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|--------------------------------------------------------------------------------------------------------------|
| DOCUMENT NO.<br>Z8B00003328                                                                                  |
| SCALE<br>0 2.0 4mm                                                                                           |
| EUROPEAN PROJECTION<br> |
| ISSUE DATE<br>19-10-2007                                                                                     |
| REVISION<br>03                                                                                               |

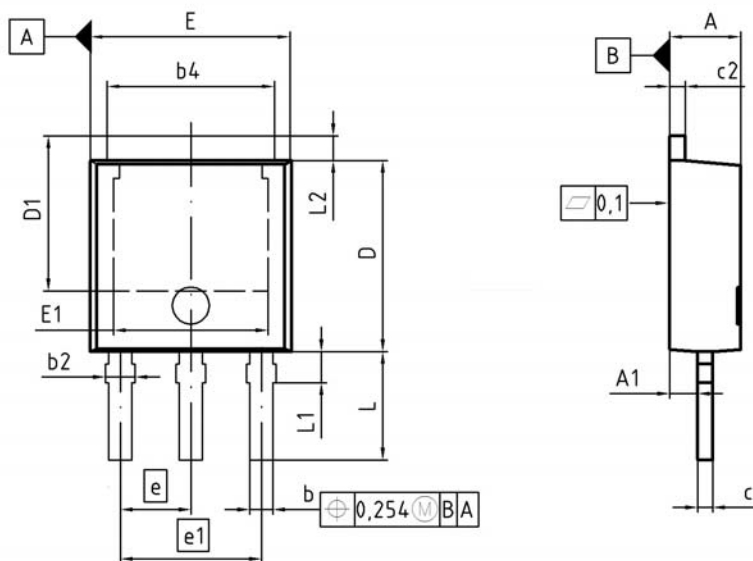
Package Outline

PG-TO252-3-23

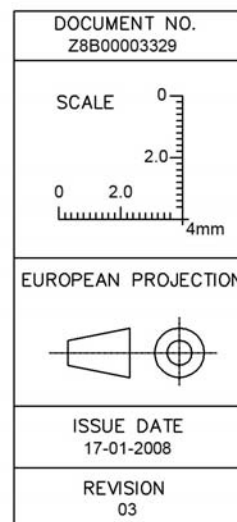


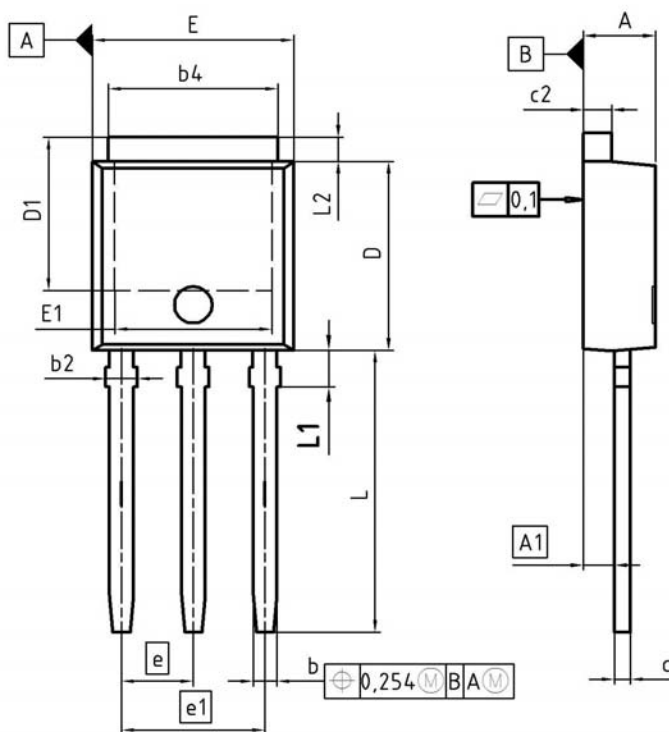
| DIM | MILLIMETERS |        | INCHES |       |
|-----|-------------|--------|--------|-------|
|     | MIN         | MAX    | MIN    | MAX   |
| A   | 2.159       | 2.413  | 0.085  | 0.095 |
| A1  | 0.000       | 0.150  | 0.000  | 0.006 |
| b   | 0.635       | 0.889  | 0.025  | 0.035 |
| b2  | 0.650       | 1.150  | 0.026  | 0.045 |
| b3  | 5.004       | 5.500  | 0.197  | 0.217 |
| c   | 0.457       | 0.580  | 0.018  | 0.023 |
| c2  | 0.460       | 0.980  | 0.018  | 0.039 |
| D   | 5.969       | 6.223  | 0.235  | 0.245 |
| D1  | 5.020       | 5.842  | 0.198  | 0.230 |
| E   | 6.400       | 6.731  | 0.252  | 0.265 |
| E1  | 4.850       | 5.207  | 0.191  | 0.205 |
| e   | 2.286       |        | 0.090  |       |
| e1  | 4.572       |        | 0.180  |       |
| N   | 3           |        | 3      |       |
| H   | 9.400       | 10.480 | 0.370  | 0.413 |
| L3  | 0.900       | 1.143  | 0.035  | 0.045 |
| L4  | 0.584       | 0.950  | 0.023  | 0.037 |
| L6  | 0.510       | 0.686  | 0.020  | 0.027 |
| F1  | 10.500      | 10.700 | 0.413  | 0.421 |
| F2  | 6.300       | 6.500  | 0.248  | 0.256 |
| F3  | 2.100       | 2.300  | 0.083  | 0.091 |
| F4  | 5.700       | 5.900  | 0.224  | 0.232 |
| F5  | 5.660       | 5.860  | 0.222  | 0.231 |
| F6  | 1.100       | 1.300  | 0.043  | 0.051 |



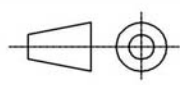


| DIM | MILLIMETERS |      | INCHES |       |
|-----|-------------|------|--------|-------|
|     | MIN         | MAX  | MIN    | MAX   |
| A   | 2.18        | 2.39 | 0.086  | 0.094 |
| A1  | 0.80        | 1.14 | 0.031  | 0.045 |
| b   | 0.64        | 0.89 | 0.025  | 0.035 |
| b2  | 0.65        | 1.15 | 0.026  | 0.045 |
| b4  | 4.95        | 5.50 | 0.195  | 0.217 |
| c   | 0.46        | 0.58 | 0.018  | 0.023 |
| c2  | 0.46        | 0.89 | 0.018  | 0.035 |
| D   | 5.97        | 6.22 | 0.235  | 0.245 |
| D1  | 5.04        | 5.44 | 0.198  | 0.214 |
| E   | 6.35        | 6.73 | 0.250  | 0.265 |
| E1  | 4.90        | 5.10 | 0.193  | 0.201 |
| e   | 2.29        |      | 0.090  |       |
| e1  | 4.57        |      | 0.180  |       |
| N   | 3           |      | 3      |       |
| L   | 3.40        | 3.60 | 0.134  | 0.142 |
| L1  | 0.90        | 1.10 | 0.035  | 0.043 |
| L2  | 0.90        | 1.10 | 0.035  | 0.043 |





| DIM | MILLIMETERS |      | INCHES |       |
|-----|-------------|------|--------|-------|
|     | MIN         | MAX  | MIN    | MAX   |
| A   | 2.16        | 2.41 | 0.085  | 0.095 |
| A1  | 0.90        | 1.14 | 0.035  | 0.045 |
| b   | 0.64        | 0.89 | 0.025  | 0.035 |
| b2  | 0.65        | 1.15 | 0.026  | 0.045 |
| b4  | 4.95        | 5.50 | 0.195  | 0.217 |
| c   | 0.46        | 0.60 | 0.018  | 0.024 |
| c2  | 0.46        | 0.89 | 0.018  | 0.035 |
| D   | 5.97        | 6.22 | 0.235  | 0.245 |
| D1  | 5.04        | 5.77 | 0.198  | 0.227 |
| E   | 6.35        | 6.73 | 0.250  | 0.265 |
| E1  | 4.70        | 5.21 | 0.185  | 0.205 |
| e   | 2.29        |      | 0.090  |       |
| e1  | 4.57        |      | 0.180  |       |
| N   | 3           |      | 3      |       |
| L   | 8.89        | 9.65 | 0.350  | 0.380 |
| L1  | 1.90        | 2.29 | 0.075  | 0.090 |
| L2  | 0.89        | 1.37 | 0.035  | 0.054 |

|                                                                                                              |
|--------------------------------------------------------------------------------------------------------------|
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| ISSUE DATE<br>19-03-2008                                                                                     |
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#### **Warnings**

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Infineon Technologies components may be used in life-support devices or systems only with the express written approval of Infineon Technologies, if a failure of such components can reasonably be expected to cause the failure of that life-support device or system or to affect the safety or effectiveness of that device or system. Life support devices or systems are intended to be implanted in the human body or to support and/or maintain and sustain and/or protect human life. If they fail, it is reasonable to assume that the health of the user or other persons may be endangered.

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